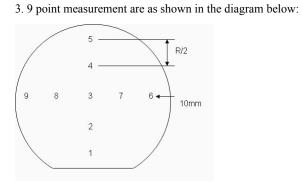
Icemos Technology Ltd Product Specification 1000.312001 Issue Date 08 August 2012 11:40

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Part Number	Customer	

Category		Parameter	Specification	Measurement Method
OverallWafer	1.0	Diameter	100.00 +/- 0.50 mm	WaferVendor
	2.0	Primary Flat Orientation	<110> +/- 1 degree	Wafer Vendor
	3.0	Primary Flat Length	32.50 +/- 2.50 mm	Wafer Vendor
	4.0	Secondary Flat Orientation	none	Wafer Vendor
	5.0	Overall Thickness	797.00 +/- 7.00 um	Guaranteed by Process
	6.0	Total Thickness Variation (TTV)	<5.00um	Guaranteed by Process
	7.0	Bow	<40.00um	Guaranteed by Process
	8.0	Warp	<40.00um	Guaranteed by Process
	9.0	Edge Exclusion	5 mm	Guaranteed by Process
HandleSilicon	10.0	Handle Growth Method	CZ	Wafer Vendor
	11.0	Handle Orientation	<111> off 2.5 - 3.5deg	Wafer Vendor
	12.0	Handle Thickness	670.00 +/- 5.00 um	Guaranteed by Process
	13.0	Handle Doping Type	P	Wafer Vendor
	14.0	Handle Dopant	Boron	Wafer Vendor
	15.0	Handle Resistivity	< 0.005	Wafer Vendor
	16.0	Backside Finish	Lapped and etched with no oxide and lasermark	Wafer Vendor
DeviceSilicon	17.0	Device Growth Method	FZ	Wafer Vendor
	18.0	Device Orientation	<111> +/- 1 degree	Wafer Vendor
	19.0	Nominal Thickness	127.00 +/- 2.00 um	Guaranteed by Process, Filmetrics 9 point, 100%
	20.0	Distance to device silicon edge from wafer edge	<= 2mm	Guaranteed by Process
	21.0	Device Doping Type	Р	Guaranteed by Process
	22.0	Device Dopant	Boron	Guaranteed by Process
	23.0	Device Resistivity	12000 - 20000 Ohmem	Wafer Vendor
	24.0	Voids	none	Guaranteed by Process, SAM inspection
	25.0	Haze	none	Guaranteed by Process, Bright LIght inspection
	26.0	Scratches	none	Guaranteed by Process, Bright LIght inspection

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Part Number		Customer			
Category	Parameter	Specification		Me	easurement Method
Shipping Details	Wafer per box :	Max 25			
	Packaging:	Taped Polypropylene Wafer Be Empak, Ultrapak, 100.00mm Antistatic Double Bagging	ox		
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness			
Explanatory Notes	1. Microscope inspec	tion performed using microscope s	can as below. 5x objec	tive.	
		pections performed exclude all waf on. High intensity bright lamp insp	-		ed in Overall



Additional Information